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#2A  
3-6-01  
1742

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

A. K. Sarkhel et al.

Serial No: ~~N/A~~ 771240

Filed: ~~Herewith~~ 1-26-0

Title: LEAD-FREE HIGH TIN TERNARY  
SOLDER ALLOY OF TIN,  
SILVER, AND BISMUTH

Group Art Unit: ~~N/A~~ 1742

Examiner: ~~N/A~~ ID

Docket No. EN995038US5

IBM Corporation  
Intellectual Property Law  
Department N50/040-4  
1701 North Street  
Endicott, NY 13760

PRELIMINARY AMENDMENT

Honorable Commissioner of Patents and Trademarks

Washington, DC 20231

Dear Sir:

Prior to initial examination on the merits, please amend the  
above-identified application as follows:

IN THE SPECIFICATION

A' On page 1, line 4, delete "The present invention" and add  
-- This application is a divisional application of serial no.  
09/216,042 which --.

IN THE CLAIMS

Please cancel claim 1-7, 11, and 12.

EN995038US5